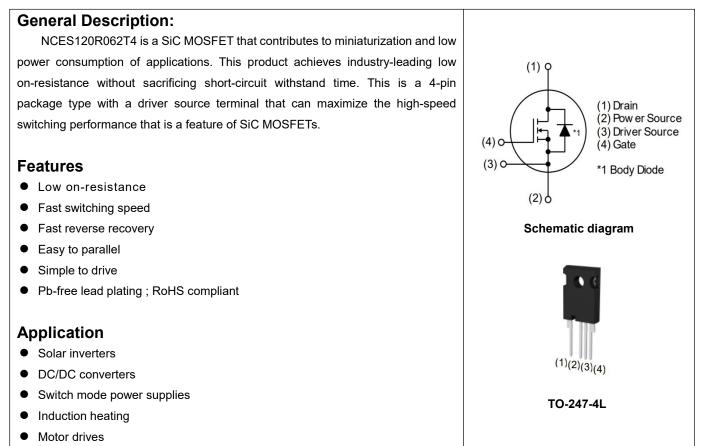


1200V, 26A, N-channel SiC power MOSFET



Package Marking and Ordering Information

Device	Device Package	Device Marking		
NCES120R062T4	TO-247-4L	NCES120R062T4		

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	1200	V
Gate-Source Voltage	Vgs	-4 to +21	V
Drain Current-Continuous ^(Note 1)	Ι _D	26	А
Drain Current-Continuous(Tc=100 ℃)	I _D (100℃)	18	А
Pulsed Drain Current (Note 1)	I _{DM}	52	А
Maximum Power Dissipation	PD	115	W
Recommended turn-on gate - source drive voltage	VGS_on	+15 to +18	V
Recommended turn-off gate - source drive voltage	VGS_off	0	V
Virtual junction temperature	T _{vj}	175	°C
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-40 To 175	°C



Thermal Characteristic

Symbol	Deremeter		Value		Units
Symbol	Parameter	Min	Тур	Max	Units
R _{θJC}	Thermal Resistance, Junction to case		0.96	1.3	°C/W

Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit
Off Characteristics	I					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =5.3mA	1200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =1200V,V _{GS} =0V	-	1	-	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =-4V / +21V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)				•		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =10V,I _D =6.45mA	2.8	-	4.8	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =18V, I _D =12A	-	58	75	mΩ
Gate input resistance	RG	f=1MHZ, open drain	-	11	-	Ω
Forward Transconductance	g Fs	V _{DS} =10V, I _D =12A		6.5		S
Dynamic Characteristics (Note 4)						
Input Capacitance	Clss	V _{DS} =800V,V _{GS} =0V,	-	1498	-	pF
Output Capacitance	Coss		-	45	-	pF
Reverse Transfer Capacitance	Crss	f=1MHz	-	3	-	pF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	4.4	-	ns
Turn-on Rise Time	tr	V _{DD} =800V,I _D =12A V _{GS} =+18V	-	11	-	ns
Turn-Off Delay Time	t _{d(off)}	/ 0V,R _G =0Ω,L=250μH	-	22	-	ns
Turn-Off Fall Time	t _f		-	10	-	ns
Total Gate Charge	Qg	V/ 000V/L 404	-	64	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =800V,I _D =12A,	-	14	-	nC
Gate-Drain Charge	Q _{gd}	- V _{GS} =18V		17	-	nC
Drain-Source Diode Characteristics					L L	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _D =12A	-	3.3	-	V
Reverse Recovery Time	t _{rr}	− T _J = 25°C, I _F =12A, V _R =800V,	-	8.1		ns
Reverse Recovery Charge	Qrr		-	105		nC
Peak reverse recovery current	Irrm	di/dt = 3800A/µs ^(Note3)		26		А

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. PW \leq 10µs, Duty cycle \leq 1%

3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

4. Guaranteed by design, not subject to production





Test Circuit

Fig.1-1 Gate Charge Measurement Circuit

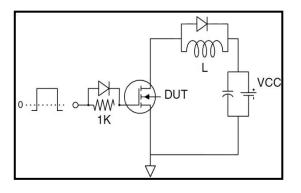


Fig.2-1 Switching Characteristics Measurement Circuit

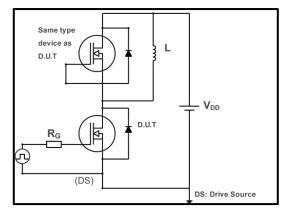


Fig.1-2 Gate Charge Waveform

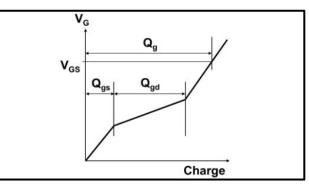
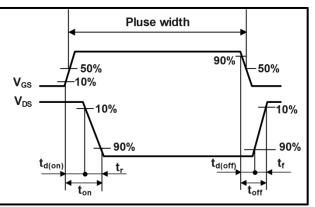


Fig.2-2 Waveforms for Switching Time





Typical Electrical and Thermal Characteristics

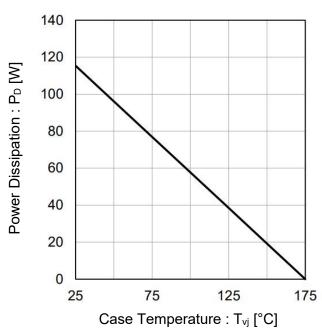


Fig.1 Power Dissipation Derating Curve

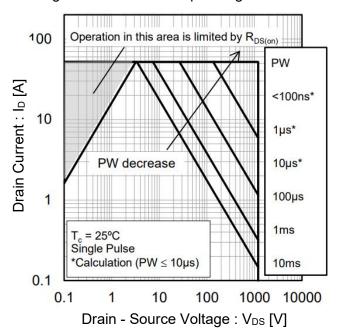
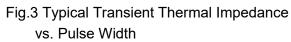
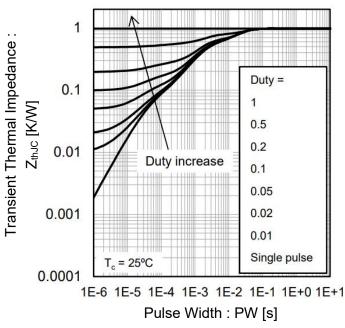


Fig.2 Maximum Safe Operating Area







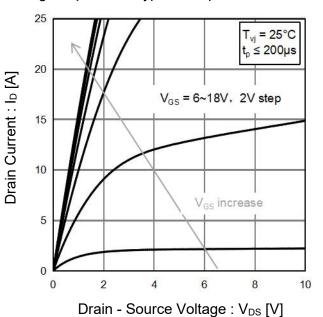


Fig.4 T_{vj} = 25° C Typical Output Characteristics

Fig.5 T_{vj} = 25°C 3rd Quadrant Characteristics

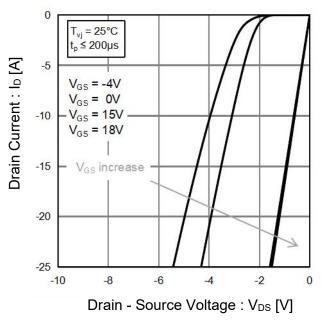


Fig.6 T_{vj} = 150° C Typical Output Characteristics

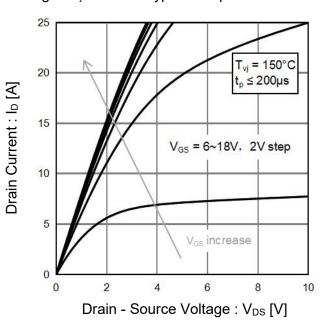
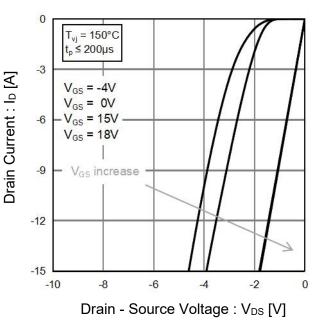


Fig.7 T_{vj} = 150°C 3rd Quadrant Characteristics







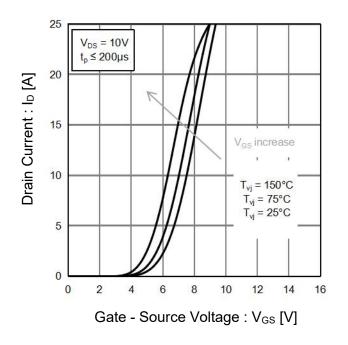


Fig.8 Typical Transfer Characteristics

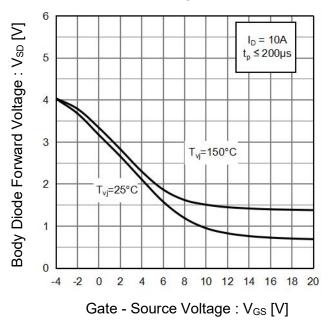


Fig.9 Body Diode Forward Voltage vs. Gate - Source Voltage

Fig.10 Gate Threshold Voltage vs. Virtual Junction Temperature

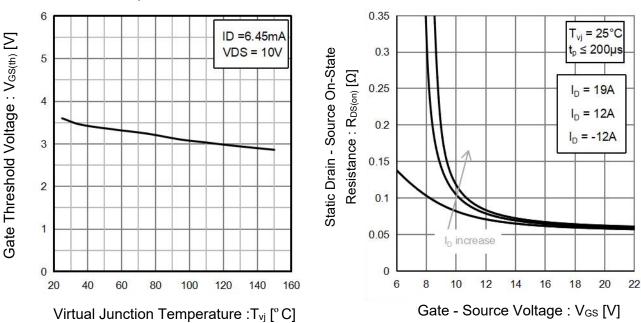
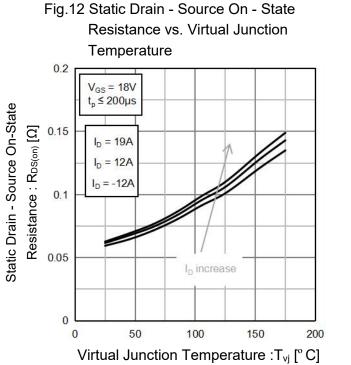


Fig.11 Static Drain - Source On - State Resistance vs. Gate - Source Voltage





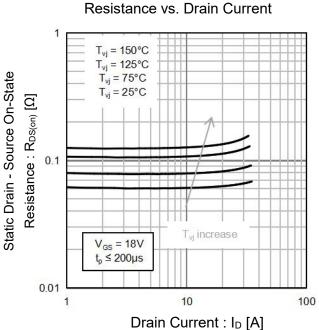


Fig.13 Static Drain - Source On - State

Fig.14 Typical Capacitance vs. Drain -Source Voltage

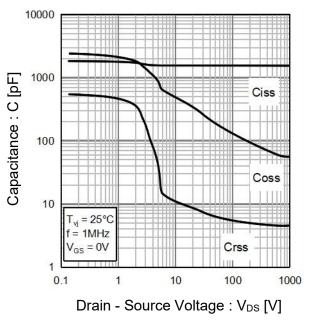
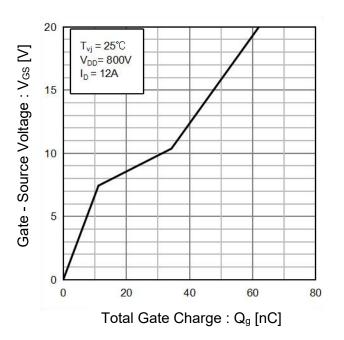


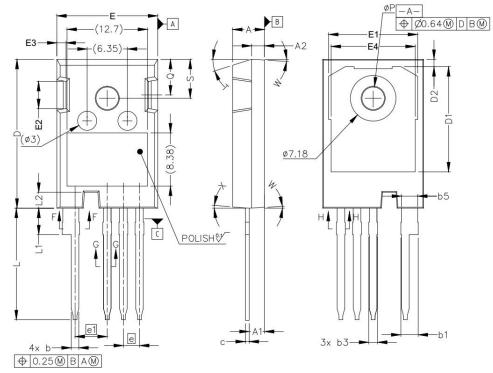
Fig.15 Dynamic Input Characteristics







TO-247-4L Package Information



O much a l	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.83	5.21	0.19	0.21	
A1	2.29	2.54	0.09	0.10	
A2	1.91	2.16	0.08	0.09	
b1	2.39	2.94	0.09	0.12	
b3	1.07	1.60	0.04	0.06	
b5	2.39	2.69	0.09	0.11	
с	0.55	0.68	0.02	0.03	
D	23.30	23.60	0.92	0.93	
D1	16.25	17.65	0.64	0.69	
D2	0.95	1.25	0.04	0.05	
E	15.75	16.13	0.62	0.64	
E1	13.10	14.15	0.52	0.56	
E2	3.68	5.10	0.14	0.20	
E3	1.00	1.90	0.04	0.07	
E4	12.38	13.43	0.49	0.53	
е	2.54	BSC	0.1	BSC	
e1	5.08	BSC	0.2 BSC		
L	17.31	17.82	0.68	0.70	
L1	3.97	4.37	0.16	0.17	
L2	2.35	2.65	0.09	0.10	
ΦΡ	3.51	3.65	0.14	0.14	
Q	5.49	6.00	0.22	0.24	
S	6.04	6.30	0.24	0.25	
Т			69° REF.		
W	3.5° REF.		0.14° REF.		
Х	4.0°	REF.	0.16°	REF.	



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